

Board Level Cooling – Surface Mount 5734



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Surface Mount 5734 is a series of surface mount board level heat sinks designed to cool Dual Flat No-Leads (DFN) packages, Quad Flat No-Leads (QFN) packages, D3 Pak, and TO-268 devices. Surface Mount 5734 can cool either a single D3 Pak, larger QFNs or DFNs, or multiple QFNs or DFNs. The tin plated surface of Surface Mount 5734 enables direct soldering to Printed Circuit Boards (PCBs) for effective board cooling.

573400D00000G is the bulk packaging option of Surface Mount 5734 and 573400D00010G is the tape and reel offering for high volume manufacturing. Representative image only.



ORDERING INFORMATION

Part Number	Device Type
573400D00000G	QFN, DFN, D3 Pak, TO-268
573400D00010G	D3 Pak/TO-268

HEAT SINK DETAILS

Property	Details
Material	Copper
Finish	Tin Plated
Device Attachment Options	-
Thermal Interface Material	-

Property	Details
Heat Sink Width (mm)	30.99
Heat Sink Length (mm)	12.70
Heat Sink Height (mm)	10.20
Heat Sink Mounting Direction	Horizontal

MECHANICAL & PERFORMANCE

Drawing dimensions are shown in mm, (in)

